

[SNAPCLEAN]

NON-CONTACT CLEANING SYSTEM WITH IONIZED AIR, ROTATING NOZZLES, AND INTEGRATED SUCTION.



TAIFUN-CLEAN® SURFACE CLEANING MODULE

Developed using **TAIFUN-CLEAN®** technology, the **[SNAPCLEAN]** module enables high-efficiency, contact-free surface cleaning for structured or 3D components.

By combining pulsating compressed air through rotating nozzles, dual ionization for electrostatic neutralization, and an integrated suction channel, it ensures a consistently clean surface prior to coating, inspection, or bonding operations.

Fully compatible with **SMART INFINITY** and other **MSTECH Europe** modular systems.

CLEAN TECHNOLOGY

- » TAIFUN-CLEAN® technology for non-contact cleaning and surface activation.
- » Rotating nozzles with four air outlets for uniform, high-turbulence airflow.
- » Integrated suction channel for efficient particle removal.
- » Dual ionization bars to neutralize electrostatic surface charges.
- » Compact design for easy integration in production lines.
- » Pressure-independent rotation control ensures stable cleaning performance.
- » Custom working widths: 100 – 2000 mm (in 100 mm increments).
- » Operating pressure: 1 – 5 bar.
- » Maximum temperature: 50 °C.
- » PCB width: Up to 600 mm.
- » PCB clearance: Up to 50 mm.